imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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DB2J208

Silicon epitaxial planar type

For high speed switching circuits

Features

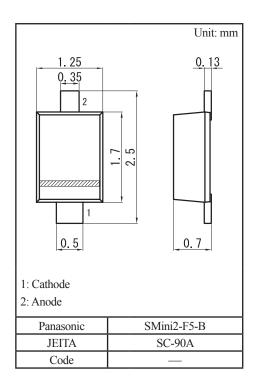
- \bullet Low forward voltage $V_{\rm F}$
- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: B8

Packaging

DB2J20800L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	20	V	
Repetitive peak reverse voltage	V _{RRM}	25	V	
Forward current (Average) *1	I _{F(AV)}	500	mA	
Non-repetitive peak forward surge current *2	I _{FSM}	2	А	
Junction temperature	Tj	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

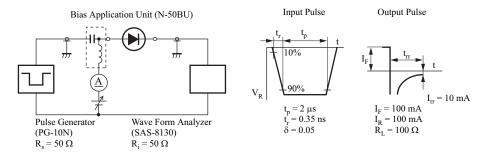
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

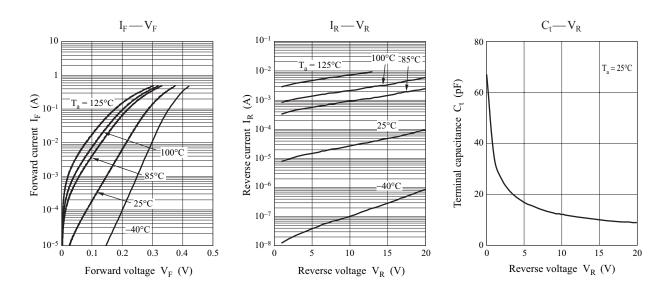
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 500 \text{ mA}$			0.42	V
Reverse current	I _R	$V_R = 20 V$			200	μΑ
Terminal capacitance	Ct	$V_{R} = 10 V, f = 1 MHz$		12		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		4.3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

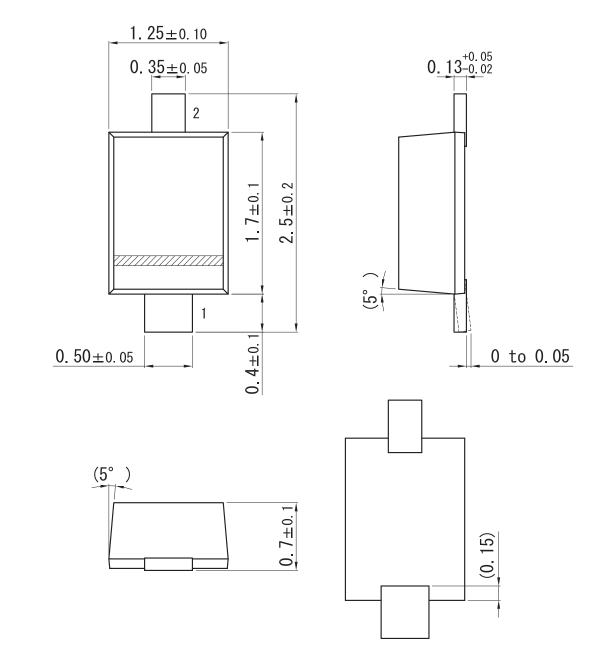
3. Absolute frequency of input and output is 250 MHz *1: t_{rr} measurement circuit



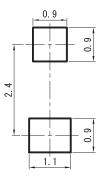


Unit: mm

SMini2-F5-B



Land Pattern (Reference) (Unit: mm)



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